



Title of Change:	SOD-323EP Surface Mount Schottky and Rectifiers Capacity Expansion with Automatic Line							
Proposed first ship date:	29 January 2019							
Contact information:	Contact your local ON Semiconductor Sales Office or <Benjo.Rulona@onsemi.com>							
Samples:	Contact your local ON Semiconductor Sales Office or <PCN.samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change.							
Additional Reliability Data:	Contact your local ON Semiconductor Sales Office or <Ken.Fergus@onsemi.com>							
Type of notification:	This is a Final Product/Process Change Notification (FPCN) sent to customers. FPCNs are issued 90 days prior to implementation of the change. ON Semiconductor will consider this change accepted, unless an inquiry is made in writing within 30 days of delivery of this notice. To do so, contact <PCN.Support@onsemi.com>							
Change Part Identification:	Cut off datecode: 0419. Current line is also retained in production							
Change Category:	<input type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input type="checkbox"/> Test Change <input type="checkbox"/> Other _____							
Change Sub-Category(s):	<input type="checkbox"/> Manufacturing Site Addition <input type="checkbox"/> Material Change <input type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input type="checkbox"/> Shipping/Packaging/Marking <input type="checkbox"/> Manufacturing Process Change <input checked="" type="checkbox"/> Other: <u>Expand capacity with automatic line</u>							
Sites Affected:	ON Semiconductor Sites: None	External Foundry/Subcon Sites: I-lan, Taiwan						
Description and Purpose:								
	<table border="1"> <thead> <tr> <th></th><th>Before Change Description</th><th>After Change Description</th></tr> </thead> <tbody> <tr> <td>Assembly Process</td><td>Semi-Automatic Assembly and Mold Processes (Current)</td><td>Semi-Automatic (Current) and New Fully Automatic Assembly and Mold Process</td></tr> </tbody> </table>		Before Change Description	After Change Description	Assembly Process	Semi-Automatic Assembly and Mold Processes (Current)	Semi-Automatic (Current) and New Fully Automatic Assembly and Mold Process	
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Assembly Process	Semi-Automatic Assembly and Mold Processes (Current)	Semi-Automatic (Current) and New Fully Automatic Assembly and Mold Process						
<p>There are no product material changes as a result of this change. All are the same. No difference in form, fit and function between products manufactured in both semi-automatic assembly and mold lines and fully automatic assembly and mold lines. This is just capacity expansion to increase productivity and meet customer demands.</p>								



Reliability Data Summary:

QV DEVICE NAME

Lots 1,2,3: NRVBSS14HE, NRVBSS16HE :

PACKAGE: SOD-323EP

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1000 hrs	0/231
H3THB	JESD22-A101	TA=85°C+/-2°C RH=85%+/-5% VR=80% rated V DC	1000 hrs	0/231
HTSL	JESD22-A103	Ta=150°C	1000 hrs	0/231
PC	J-STD-020 JESD-A113	MSL1 @ 260 °C		0/693
IOL	MIL-STD-750 (M1037) AEC-Q101	I=IF±10% DC supply On time: 2 mins at least , Off time : 2 mins at least	15000 cyc	0/231
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
AC	JESD-A102	TA= 121°C, P= 15psig Relative Humidity = 100%	96 hrs	0/231
RSH	JESD22- B106	Ta = 260±5°C, 10±1sec; Dipping depth=within 1.27mm of the body		0/90
SD	JSTD002	Ta = 245±5C, 5±0.5 sec		0/30

QV DEVICE NAME

Lots 4,5,6: S1JHE:

PACKAGE: SOD-323EP

Test	Specification	Condition	Interval	Results
HTRB	JESD22-A108	Ta=150°C, 100% max rated V	1000 hrs	0/231
H3THB	JESD22-A101	TA=85°C+/-2°C RH=85%+/-5% VR=80% rated V DC	1000 hrs	0/231
HTSL	JESD22-A103	Ta=150°C	1000 hrs	0/231
PC	J-STD-020 JESD-A113	MSL1 @ 260 °C		0/693
IOL	MIL-STD-750 (M1037) AEC-Q101	I=IF±10% DC supply On time: 2 mins at least , Off time : 2 mins at least	15000 cyc	0/231
TC	JESD22-A104	Ta= -55°C to +150°C	1000 cyc	0/231
AC	JESD-A102	TA= 121°C, P= 15psig Relative Humidity = 100%	96 hrs	0/231
RSH	JESD22- B106	Ta = 260±5°C, 10±1sec; Dipping depth=within 1.27mm of the body		0/90
SD	JSTD002	Ta = 245±5C, 5±0.5 sec		0/30

**Electrical Characteristic Summary:**

Electrical characteristics are not impacted.

List of Affected Parts:

Part Number	Qualification Vehicle
S1GHE	S1JHE
S1JHE	S1JHE
SS13HE	NRVBSS14HE
SS14HE	NRVBSS14HE
SS16HE	NRVBSS16HE